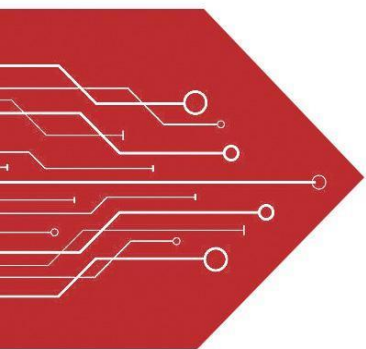


MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT

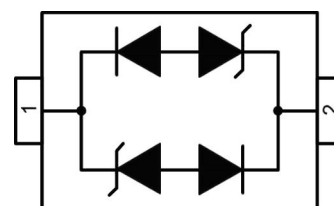
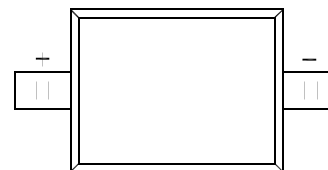


PLED

Product data sheet

Features

- ◆ 350W peak pulse power (8/20μs)
- ◆ Ultra low capacitance : 1.0pF typical
- ◆ Ultra low leakage: nA level
- ◆ Low Operating: 3.3V,5V,8V,12V,15V,24V
- ◆ Low clamping voltage
- ◆ Protects one power line or data line
- ◆ Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: ±30kV
 - Contact discharge: ±30kV
 - IEC61000-4-4 (EFT) 40A (5/50ns)
- ◆ RoHS Compliant



Circuit and Pin Schematic

Mechanical Characteristics

- ◆ Package: SOD-323
- ◆ Lead Finish: Matte Tin
- ◆ Case Material: “Green” Molding Compound.
- ◆ UL Flammability Classification Rating 94V-0
- ◆ Moisture Sensitivity: Level 3 per J-STD-020
- ◆ Terminal Connections: See Diagram Below
- ◆ Marking Information: See Below

SOD-323

Applications

- ◆ USB Ports
- ◆ Smart Phones
- ◆ Wireless Systems
- ◆ Ethernet 10/100/1000 Base T

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
ESD per IEC 61000-4-2 (Air)	VESD	±30	kV
ESD per IEC 61000-4-2 (Contact)		±30	
Operating Temperature Range	TJ	-40 to +85	°C
Storage Temperature Range	Tstg	-55 to +150	°C

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

BV03C-MS						
Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	VRWM			3.3	V	
Breakdown Voltage	VBR	4			V	$I_T = 1\text{mA}$
Reverse Leakage Current	I_R		1	100	nA	$VRWM = 3.3\text{V}$
Clamping Voltage	VC			7	V	$I_{PP} = 1\text{A}$ (8 x 20 μs pulse)
Clamping Voltage	VC			16	V	$I_{PP} = 20\text{A}$ (8 x 20 μs pulse)
Peak Pulse Current	I_{PP}			20	A	$t_p=8/20\mu\text{s}$
Junction Capacitance	CJ		1		pF	$VR = 0\text{V}$, $f = 1\text{MHz}$

BV05C-MS						
Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	VRWM			5	V	
Breakdown Voltage	VBR	6			V	$I_T = 1\text{mA}$
Reverse Leakage Current	I_R		1	100	nA	$VRWM = 5\text{V}$
Clamping Voltage	VC			10	V	$I_{PP} = 1\text{A}$ (8 x 20 μs pulse)
Clamping Voltage	VC			18	V	$I_{PP} = 18\text{A}$ (8 x 20 μs pulse)
Peak Pulse Current	I_{PP}			18	A	$t_p=8/20\mu\text{s}$
Junction Capacitance	CJ		1		pF	$VR = 0\text{V}$, $f = 1\text{MHz}$

BV08C-MS

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	VRWM			8	V	
Breakdown Voltage	VBR	8.5			V	IT = 1mA
Reverse Leakage Current	IR		1	100	nA	VRWM = 8V
Clamping Voltage	VC			14	V	I _{PP} = 1A (8 x 20μs pulse)
Clamping Voltage	VC			19	V	I _{PP} = 13A (8 x 20μs pulse)
Peak Pulse Current	I _{PP}			13	A	tp=8/20μs
Junction Capacitance	CJ		1		pF	VR = 0V, f = 1MHz

BV12C-MS

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	VRWM			12	V	
Breakdown Voltage	VBR	13.3			V	IT = 1mA
Reverse Leakage Current	IR		1	100	nA	VRWM = 12V
Clamping Voltage	VC			19	V	I _{PP} = 1A (8 x 20μs pulse)
Clamping Voltage	VC			25	V	I _{PP} = 10A (8 x 20μs pulse)
Peak Pulse Current	I _{PP}			10	A	tp=8/20μs
Junction Capacitance	CJ		1		pF	VR = 0V, f = 1MHz

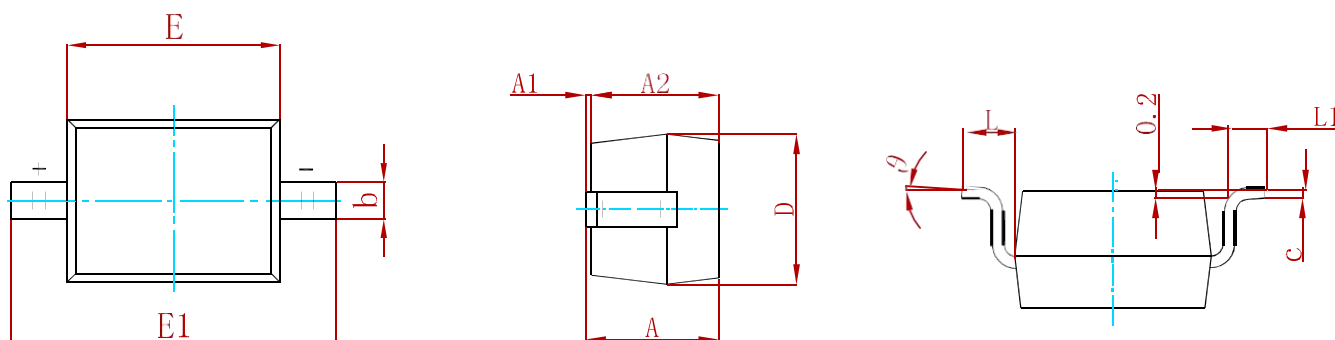
BV15C-MS

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	VRWM			15	V	
Breakdown Voltage	VBR	16.7			V	IT = 1mA
Reverse Leakage Current	IR		1	100	nA	VRWM = 15V
Clamping Voltage	VC			20	V	I _{PP} = 1A (8 x 20μs pulse)
Clamping Voltage	VC			31	V	I _{PP} = 8A (8 x 20μs pulse)
Peak Pulse Current	I _{PP}			8	A	t _p =8/20μs
Junction Capacitance	C _J		1		pF	VR = 0V, f = 1MHz

BV24C-MS

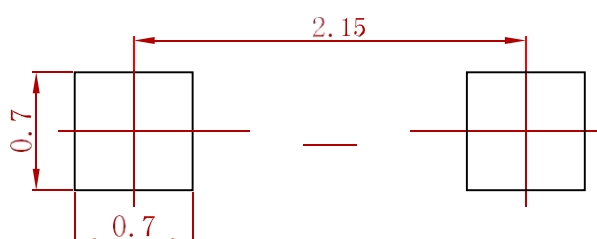
Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	VRWM			24	V	
Breakdown Voltage	VBR	26.7			V	IT = 1mA
Reverse Leakage Current	IR		1	100	nA	VRWM = 24V
Clamping Voltage	VC			40	V	I _{PP} = 1A (8 x 20μs pulse)
Clamping Voltage	VC			71	V	I _{PP} = 3.5A (8 x 20μs pulse)
Peak Pulse Current	I _{PP}			3.5	A	t _p =8/20μs
Junction Capacitance	C _J		1		pF	VR = 0V, f = 1MHz

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BVXXC-MS	SOD-323	3000

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